

LISTING OF CLAIMS

The present Listing consists of all claims to be examined and supercedes any prior listing of claims.

1-37. (Cancelled).

38. (Previously presented). An apparatus comprising:

a dielectric substrate;

a metallic surface on said dielectric substrate;

a layer of a first polymer provided on said metallic surface, said first polymer being a water-soluble, cationic material having a weight average molecular weight of about 100,000; and

a layer of a second polymer provided on said first polymer, said second polymer being a non-water-soluble material.

39. (Previously presented). The apparatus of Claim 1, wherein said metallic surface is selected from the group consisting of copper, gold, aluminum, silver, titanium, tantalum, tungsten, niobium, alloys thereof, silicides thereof, and intermetallic compounds thereof.

40. (Previously presented). The apparatus of Claim 1, wherein said metallic surface is copper.

41. (Previously presented). The apparatus of Claim 1, wherein said metallic surface is gold.

42. (Previously presented). The apparatus of Claim 1, wherein said second polymer is selected from the group consisting of polymers of acrylates and methacrylates.

43. (Previously presented). The apparatus of Claim 1, wherein said first polymer is selected from the group consisting of polymers of acrylamides and amidoamines.

44. (Previously presented). The apparatus of Claim 1, wherein said first polymer has a weight average molecular weight of from about 500,000 to about 1,000,000.

45. (Previously presented). The apparatus of Claim 1, wherein said layer of a first polymer is a monolayer.

46. (Previously presented). The apparatus of Claim 1, wherein said layer of a first polymer is less than a monolayer.

47. (Previously presented). The apparatus of Claim 1, wherein said layer of a first polymer covers at least 25% of said metallic surface.